

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	Patent Security Agreement

CONVEYING PARTY DATA

Name	Execution Date
Avantor Performance Materials, Inc.	10/08/2010

RECEIVING PARTY DATA

Name:	Credit Suisse AG, Cayman Island Branch
Street Address:	Eleven Madison Avenue
City:	New York
State/Country:	NEW YORK
Postal Code:	10010

PROPERTY NUMBERS Total: 44

Property Type	Number
Patent Number:	6203679
Patent Number:	5217619
Patent Number:	5308745
Patent Number:	6749998
Patent Number:	6326130
Patent Number:	5466389
Patent Number:	5498293
Patent Number:	5576217
Patent Number:	5989353
Patent Number:	6585825
Patent Number:	6465403
Patent Number:	6599370
Patent Number:	6311134
Patent Number:	6899818
Patent Number:	6875817

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Patent Number:	7393819
Patent Number:	7247208
Patent Number:	7718591
Patent Number:	7419945
Patent Number:	7671001
Patent Number:	7470767
Patent Number:	7521406
Patent Number:	7767636
Patent Number:	7754668
Patent Number:	7375188
Application Number:	11630603
Application Number:	11630602
Application Number:	11719690
Application Number:	11817874
Application Number:	12565172
Application Number:	11720084
Application Number:	11910281
Application Number:	12161886
Application Number:	11521246
Application Number:	12046582
Application Number:	12522605
Application Number:	12522716
Application Number:	12596921
Application Number:	12600369
Application Number:	12619259
Application Number:	61292556
Application Number:	61320848
Application Number:	11813434
Application Number:	11349635

CORRESPONDENCE DATA

Fax Number: (917)777-4104
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: 212-735-3000
Email: mmcguire@skadden.com
Correspondent Name: Skadden Arps Slate Meagher & Flom LLP

Address Line 1: Four Times Square
Address Line 2: Attn: Shivram Sankar, Esq.
Address Line 4: New York, NEW YORK 10036

ATTORNEY DOCKET NUMBER: 217730/2332

NAME OF SUBMITTER: Shivram Sankar

Total Attachments: 7

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PATENT SECURITY AGREEMENT

PATENT SECURITY AGREEMENT dated as of October 8, 2010 (this "**Agreement**"), among AVANTOR PERFORMANCE MATERIALS, INC., a New Jersey Corporation (the "**Grantor**"), located at 222 Red School Lane, Phillipsburg, NJ 08865, and CREDIT SUISSE AG, CAYMAN ISLANDS BRANCH ("**CS**"), as collateral agent (in such capacity, the "**Collateral Agent**").

Reference is made to (a) the Guarantee and Collateral Agreement dated as of the date hereof (as amended, supplemented or otherwise modified from time to time, the "**Guarantee and Collateral Agreement**"), among the Borrower, Holdings, the Subsidiary Guarantors from time to time party thereto and the Collateral Agent and (b) the Credit Agreement dated as of the date hereof (as amended, restated, supplemented or otherwise modified from time to time, the "**Credit Agreement**"), among the Borrower, Holdings, the Lenders party thereto and CS, as administrative agent and collateral agent. The Lenders have agreed to extend credit to the Borrower subject to the terms and conditions set forth in the Credit Agreement. The obligations of the Lenders to extend such credit are conditioned upon, among other things, the execution and delivery of this Agreement. Each Grantor (other than the Borrower) is an affiliate of the Borrower, will derive substantial benefits from the extensions of credit to the Borrower pursuant to the Credit Agreement and is willing to execute and deliver the Guarantee and Collateral Agreement and this Agreement in order to induce the Lenders to extend such credit. Pursuant to the Guarantee and Collateral Agreement, the Grantor is required to execute and deliver this Agreement. Accordingly, the parties hereto agree as follows:

SECTION 1. Terms. Each capitalized term used but not defined in this Agreement has the meaning given or ascribed to it in the Guarantee and Collateral Agreement. The rules of construction specified in Section 1.01(b) of the Guarantee and Collateral Agreement also apply to this Agreement.

SECTION 2. Grant of Security Interest. As security for the payment or performance, as the case may be, in full of the Obligations, each Grantor hereby pledges to the Collateral Agent, its successors and assigns, for the ratable benefit of the Secured Parties, and hereby grants to the Collateral Agent, its successors and assigns, for the ratable benefit of the Secured Parties, a security interest in all right, title or interest in or to any and all of the following assets and properties now owned or at any time hereafter acquired by such Grantor or in which such Grantor now has or at any time in the future may acquire any right, title or interest (collectively, the "**Patent Collateral**"):

- (a) all patents issued by the United States or the equivalent thereof in any other country, and all applications for patents of the United States or the equivalent thereof in any other country, including issued patents and pending applications in the United States Patent and Trademark Office (or any successor or any similar offices in any other country), including those listed on Schedule I;

(b) all reissues, continuations, divisions, continuations-in-part, renewals or extensions thereof, and the inventions disclosed or claimed therein, including the right to make, use and/or sell the inventions disclosed or claimed therein ((a) and (b) collectively, the “*Patents*”); and

(c) all Proceeds and products of any and all of the foregoing, all Supporting Obligations and all collateral security and guarantees given by any Person with respect to any of the foregoing.

SECTION 3. Recordation. This Agreement has been executed and delivered by each Grantor for the purpose of recording the grant of security interest herein with the United States Patent and Trademark Office. Each Grantor authorizes and requests that the Commissioner of Patents and Trademarks record this Agreement.

SECTION 4. Guarantee and Collateral Agreement. The security interests granted to the Collateral Agent herein are granted in furtherance, and not in limitation of, the security interests granted to the Collateral Agent pursuant to the Guarantee and Collateral Agreement. Each Grantor hereby acknowledges and affirms that the rights and remedies of the Collateral Agent with respect to the Patent Collateral are more fully set forth in the Guarantee and Collateral Agreement, the terms and provisions of which are hereby incorporated herein by reference as if fully set forth herein. In the event of any conflict between the terms of this Agreement and the Guarantee and Collateral Agreement, the terms of the Guarantee and Collateral Agreement shall govern, and for the avoidance of doubt, Patent Collateral shall not include any Excluded Assets.

SECTION 5. Counterparts. This Agreement may be executed in counterparts (and by different parties hereto on different counterparts), each of which shall constitute an original but all of which when taken together shall constitute a single contract. Delivery of an executed signature page to this Agreement by facsimile transmission shall be as effective as delivery of a manually signed counterpart of this Agreement.

SECTION 6. Further Assurances. Each Grantor further agrees to execute and deliver to the Collateral Agent any and all further documents and instruments, and do any and all further acts which the Collateral Agent (or the Collateral Agent’s agents or designees) reasonably requests in order to confirm this grant of security interest in and to the Patent Collateral.

SECTION 7. Applicable Law. THIS AGREEMENT SHALL BE CONSTRUED IN ACCORDANCE WITH AND GOVERNED BY THE LAWS OF THE STATE OF NEW YORK.

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IN WITNESS WHEREOF, the parties hereto have duly executed this Agreement
as of the day and year first above written.

AVANTOR PERFORMANCE
MATERIALS, INC.


By: *Robert Harrer*
Name: *Robert Harrer*
Title: *Vice President and Treasurer*


[SIGNATURE PAGE TO PATENT SECURITY AGREEMENT]

PATENT
REEL: 025114 FRAME: 0213

Acknowledged and Agreed by:

CREDIT SUISSE AG,
CAYMAN ISLANDS BRANCH,

By: 
Name: JOHN D. TORONTO
Title: DIRECTOR

By: 
Name: VIPUL DHADDA
Title: ASSOCIATE

[SIGNATURE PAGE TO PATENT SECURITY AGREEMENT]

**SCHEDULE I TO
PATENT SECURITY AGREEMENT**

Patents and Patent Applications

Country	Title	Appl. No.	Filing Date	Patent No.	Issue Date	Status
United States	Electrophoresis Gel Container	09/251129	16-Feb-99	6203679	20-Mar-01	Granted
United States	Liquid-Solid Extraction Apparatus And Method Of Using Same	846895	06-Mar-92	5217619	08-Jun-93	Granted
United States	Alkaline-Containing Photoresist Stripping Compositions Producing Reduced Metal Corrosion With Cross-Linked Or Hardened Resist Resins	972511	06-Nov-92	5308745	03-May-94	Granted
United States	Photoresist Strippers Containing Reducing Agents To Reduce Metal Corrosion	09/968665	02-Oct-01	6749998	15-Jun-04	Granted
United States	Photoresist Strippers Containing Reducing Agents To Reduce Metal Corrosion	133680	07-Oct-93	6326130	04-Dec-01	Granted
United States	Ph Adjusted Nonionic Surfactant-Containing Alkaline Cleaner Composition For Cleaning Microelectronics Substrates	230132	20-Apr-94	5466389	14-Nov-95	Granted
United States	Cleaning Wafer Substrates Of Metal Contamination While Maintaining Wafer Smoothness	264858	23-Jun-94	5498293	12-Mar-96	Granted
United States	Solid Phase Microextraction Of Trace Amounts Of Organic Analytes	396124	28-Feb-95	5576217	19-Nov-96	Granted
United States	Cleaning Wafer Substrates Of Metal Contamination While Maintaining Wafer Smoothness	08/729565	11-Oct-96	5989353	23-Nov-99	Granted
United States	Stabilized Containing Alkaline Compositions For Cleaning Microelectronic Substrates	09/688559	16-Oct-00	6585825	01-Jul-03	Granted
United States	Silicate-Containing Alkaline Compositions For Cleaning Microelectronic Substrates	09/701114	17-Nov-00	6465403	15-Oct-02	Granted
United States	Stabilized Alkaline Compositions For Cleaning Microelectronic Substrates	09/859142	16-May-01	6599370	29-Jul-03	Granted
United States	Process And Apparatus For Comparing Chemical Products	09/247058	09-Feb-99	6311134	30-Oct-01	Granted
United States	Method And Composition For Removing Sodium-Containing Material From Microcircuit Substrates	10/220720	04-Sep-02	6899818	31-May-05	Granted
United States	Functionalized Polymeric Media For Separation Of Analytes	10/250570	12-Feb-03	6875817	05-Apr-05	Granted
United States	Ammonia-Free Alkaline Microelectronic Cleaning Compositions With Improved Substrate Compatibility	10/483037	06-Jan-04	7393819	01-Jul-08	Granted
United States	Microelectronic Cleaning Compositions Containing Ammonia-Free Fluoride Salts For Selective Photoresist Stripping And Plasma Rich Residue Cleaning	10/483036	06-Jan-04	7247208	24-Jul-07	Granted
United States	Microelectronic Cleaning Compositions Containing Ammonia-Free Fluoride Salts For Selective Photoresist Stripping And Plasma Rich Residue Cleaning	11/762087	13-Jun-07	7718591	18-May-10	Granted

Country	Title	Appl. No.	Filing Date	Patent No.	Issue Date	Status
United States	Microelectronic Cleaning Compositions Containing Oxidizers And Organic Solvents	10/515392	22-Nov-04	7419945	02-Sep-08	Granted
United States	Alkaline, Post Plasma Etch Or Post Etch/Ash Residue Removers And Photoresist Strippers Containing Metal-Halide Corrosion Inhibitors	10/572860	22-Mar-06	7671001	02-Mar-10	Granted
United States	Preparation Of Ultrapure Polymeric Articles	11/631586	04-Jan-07	7470767	30-Dec-08	Granted
United States	Chromatographic Media	11/813434	06-Jul-07			Published
United States	Stripping And Cleaning Compositions For Microelectronics	11/349635	08-Feb-06			Published
United States	Microelectronic Cleaning Compositions Containing Halogen Oxygen Acids, Salts, And Derivatives	10/982330	05-Nov-04	7521406	21-Apr-09	Granted
United States	Nanoelectronic And Microelectronic Cleaning Compositions	10/584827	27-Jun-06	7767636	03-Aug-10	Issued
United States	Compositions For The Removal Of Post-Etch And Ashed Photoresist Residues And Bulk Photoresist	11/911346	12-Oct-07	7754668	13-Jul-2010	Issued
United States	Compositions For Cleaning Microelectronic Substrates	11/630603	20-Dec-06			Published
United States	Non-Aqueous Microelectronic Cleaning Compositions Containing Fructose	11/630602	20-Dec-06			Published
United States	Non-Aqueous, Non-Corrosive Microelectronic Cleaning Compositions Containing Polymeric Corrosion Inhibitors	11/719690	18-May-07			Published
United States	Compositions For Cleaning Ion Implanted Photoresist In Front End Of Line Applications	11/817874	06-Sep-07			Published
United States	High Efficiency Chromatography Column With Re-Usable End Cap	12/565172	23-Sep-09			Published
United States	Non-Aqueous, Non-Corrosive Microelectronic Cleaning Compositions	11/720084	24-May-07			Published
United States	Non-Aqueous Photoresist Stripper That Inhibits Galvanic Corrosion	11/910281	01-Oct-07			Published
United States	Stabilized Non-Aqueous Cleaning Compositions For Microelectronic Substrates	12/161886	23-Jul-08			Published
United States	Purified Vegetarian Protein A And Process For Production Thereof	11/521246	14-Sep-06			Pending
United States	Vegetarian Protein A Preparation And Methods Thereof	11/194093	29-Jul-05	7375188	20-May-08	Granted
United States	Vegetarian Protein A Preparation And Methods Thereof	12/046582	12-Mar-08			Published
United States	Chromatographic Media Storage Solution Composition And Use Thereof	12/522605	09-Jul-09			Published
United States	Peroxide Activated Oxometalate Based Formulation For Removal Of Etch Residue	12/522716	10-Jul-09			Published
United States	Polysilicon Planarization Solution For Planarizing Low Temperature Poly-Silicon Thin Film Panels	12/596921	21-Oct-09			Pending

Country	Title	Appl. No.	Filing Date	Patent No.	Issue Date	Status
United States	Directly Compressible High Functionality Granular Microcrystalline Based Co-Processed Excipient, Manufacturing Process And Use Thereof	12/600369	16-Nov-09			Pending
United States	Directly Compressible High Functionality Granular Microcrystalline Based Co-Processed Excipient, Manufacturing Process And Use Thereof	12/619259	16-Nov-09			Published
United States	Chemical Compositions For Wet Chemical Modification Of Sapphire Surfaces	61/292556	06-Jan-10			Pending
United States	Process For Trypsin And Chymotrypsin Purification Utilizing Hydrophobic Interaction Chromatography	61/320848	05-Apr-10			Pending